

## **IN THE CLAIMS**

### **Amendments To The Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

### **Listing of Claims:**

1. (Currently Amended) A module comprising:  
a substrate; and  
a plurality of semiconductor packages, each comprising a semiconductor chip, mounted on the substrate;  
wherein each of the plurality of semiconductor packages comprises a first radio communication element ~~for transmitting and receiving that is constituted independently of the semiconductor chip so as to transmit and receive a signal between the~~ semiconductor chips in the plurality of semiconductor packages by radio communication, and  
the first radio communication element ~~is constituted independently of the semiconductor chip~~ comprises an antenna and an RF circuit.
2. (Original) The module according to claim 1, wherein each of the plurality of semiconductor packages further comprises a resin portion for sealing the semiconductor chip.
3. (Original) The module according to claim 1, wherein each of the plurality of semiconductor packages further comprises a resin portion for sealing the semiconductor chip, and  
the first radio communication element is provided inside or on a surface of the resin portion.
4. (Original) The module according to claim 1, wherein each of the plurality of semiconductor packages further comprises a shielding layer for blocking an

electromagnetic wave.

5. (Original) The module according to claim 1, wherein each of the plurality of semiconductor packages further comprises a shielding layer for blocking an electromagnetic wave in a part of a surface of the first radio communication element.

Claims 6-7. (Cancelled)

8. (Original) The module according to claim 1, wherein the substrate is a single-sided substrate obtained by forming a conductor pattern on only one principal surface of a base or a double-sided substrate obtained by forming a conductor pattern on both principal surfaces of the base, and  
each of the plurality of semiconductor packages is mounted on the conductor pattern.

9. (Original) The module according to claim 8, wherein the conductor pattern is constituted by at least one terminal selected from the group consisting of a power source terminal and a ground terminal.

Claims 10-11. (Cancelled)